

**NOTES:**

**1. MATERIAL:**

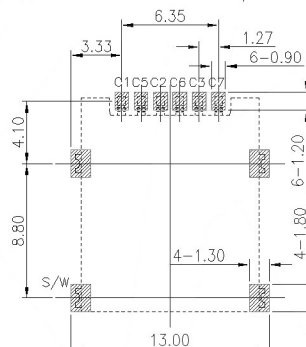
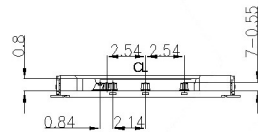
- 1.1 Housing: High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Terminal: Copper Alloy, T=0.12mm.
- 1.3 Shell: SUS, T=0.20mm.

**2. FINISH:**

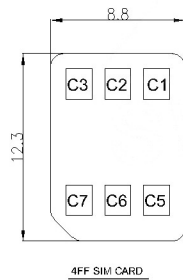
- 2.1 Terminal: Plated Gold on the Contact Area and Solder Tails
- 2.2 Peg: Plated Gold on the Solder Tails.

**3. SPECIALITY:**

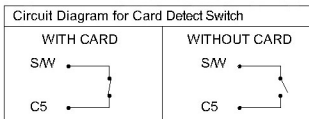
- 3.1 Rated current: 0.5A
- 3.2 Rated voltage: 50V
- 3.3 Contact Resistance: 50mΩ MAX
- 3.4 Insulation Resistance: 100MΩ MIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Durability Cycles: 5000 Cycles.
- 3.7 Solder ability: 245±5°C, 5±0.5s.
- 3.8 Operating condition: Temperature: -30°C +80°C  
Humidity: 80% R.H MAX



**RECOMMENDED PCB LAYOUT**  
TOLERANCE ±0.05  
SMT SOLDER AREA



PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	Switch Pin



ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
ΔX					ANGULAR ±5°
ΔX					L ≤ 4 ±0.2
ΔX					4 < L ≤ 16 ±0.3
					16 < L ≤ 63 ±0.4
					L > 63 ±0.5

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	SIM CARD CONN
CHKD	DATE	UNIT: mm	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			<b>XKNANO-1306</b>
			WEIGHT SHEET REVISION
			1.0g 1/1 A0

Kosod Technology Co., Ltd.